

Qualification Results Summary of LTM4624, LTM4625 with revised substrate and Sumitomo G311E mold compound

QUALIFICATION STATUS – LTM4625 BGA			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
Unbiased Highly Accelerated Stress Test (UHAST)*	JEDEC <i>JESD22-A102</i>	1*77	Pass
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	1*77	Pass
Thermal Shock (TS)*	JEDEC <i>JESD22-A106</i>	1*77	Pass
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	1*231	Pass

*Preconditioned per JEDEC/IPC J-STD-020 MSL3 (@250C)